Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT INFORMATION NOTIFICATION

PIN: PIN200901 **Date:** February 26, 2020

Subject: Qualification of Amkor Technology Japan Usuki Site for 300mm DPS Process for Select MCU Products

To: FUTURE ELECTRONICS
FUTURE ELE
pcn.system2@future.ca

Change Type: Minor

Description of Change:
Cypress announces the qualification of Amkor Technology Japan Usuki (ATJ, 1913-2, Takegashita, Fukura, Usuki-shi,Oita 875-0053, Japan) as a new Die Processing Service (DPS) site for select MCU Products. The current products are processed at Amkor Technology Japan Kitsuki (ATJ, 2820-2, Minami-Kitsuki, Kitsuki-shi, Oita 873-0002, Japan). The change corresponds to Category (DPS Usuki) in APCN194303.

Amkor Technology Japan Usuki is certified by international quality standards, ISO 9001 and IATF16949. Amkor Technology Japan certificates can be viewed on their corporate web site below: https://amkor.com/quality-management/

Benefit of Change:
Cypress will have the added capability to meet varying market demand, and to ensure consistent and reliable delivery performance to customers.

Part Numbers Affected: 109
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PIN will include all changes outlined in this PIN.

Qualification Status:
This DPS site has been qualified through a series of tests documented in Qualification Test Plan QTP#193212. This qualification report can be found as an attachment to this PCN.

QTP Number	Qualification
193212	DPS Line, 300mm Wafer, Amkor Technology Japan Usuki Site

Approximate Implementation Date:
Effective 90 days from the date of this notification, all shipments of the affected part numbers in the attached file will be supplied from Amkor Technology Japan Usuki.

Anticipated Impact:
No impact is expected in datasheet parameters, package composition and package pin-out.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration

Cypress Semiconductor
Package Qualification Report

QTP# 193212, 193210, 193211 VERSION **
January, 2020

DPS Line, 300mm wafer,

Amkor Technology Japan Usuki Site

(DPS : Die Processing Service)

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PACKAGE/PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
193212	Qualification of DPS Line at Usuki and assembly at Fukuoka site	January, 2020
193210	Qualification of DPS Line at Usuki and assembly at Fukuoka site	January, 2020
193211	Qualification of DPS Line at Usuki and assembly at Usuki site	January, 2020

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualification of DPS Line at Usuki and assembly at Fukuoka site	
Marketing Part #:	CY9BFD18TPMC-GK7MJE1
Device Description:	General purpose single-chip products
Cypress Division:	Microcontroller and Connectivity Division

PACKAGE	ASSEMBLY FACILITY SITE
176-pin LQFP	**Amkor Technology Japan – Fukuoka (DPS at Usuki)**

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	LQP176
Package Outline, Type, or Name:	176 – Low Profile Quad Flat Package
Mold Compound Name/Manufacturer:	EME-G660B / Sumitomo
Mold Compound Flammability Rating:	V-0
Lead Frame Material:	Copper Alloy
Lead Finish, Composition / Thickness:	Sn-Bi Plating (5 – 20um)
Die Backside Preparation Method/Metallization:	Si Back Grind
Die Separation Method:	Dicing
Die Attach Supplier:	Hitachi
Die Attach Material:	EN4600B
Wire Bond Method:	Ultrasonic & Force
Package Cross Section Yes/No:	Yes
Name/Location of Assembly (prime) facility:	Amkor Technology Japan – Fukuoka (DPS at Usuki)
MSL LEVEL	3
REFLOW PROFILE	260°C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	**Amkor Technology Japan – Fukuoka**

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualification of DPS Line at Usuki and assembly at Fukuoka site	
Marketing Part #:	S6J32GEKSMEE2000A
Device Description:	General purpose single-chip products
Cypress Division:	Microcontroller and Connectivity Division

PACKAGE	ASSEMBLY FACILITY SITE
208-pin TEQFP	**Amkor Technology Japan – Fukuoka (DPS at Usuki)**

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	LET208
Package Outline, Type, or Name:	208 – Low Profile Quad Flat Package with exposed pad
Mold Compound Name/Manufacturer:	EME-G660B / Sumitomo
Mold Compound Flammability Rating:	V-0
Lead Frame Material:	Copper Alloy
Lead Finish, Composition / Thickness:	Pure-Sn Plating (7 – 20um)
Die Backside Preparation Method/Metallization:	Si Back Grind
Die Separation Method:	Dicing
Die Attach Supplier:	Hitachi
Die Attach Material:	EN4600B
Wire Bond Method:	Ultrasonic & Force
Package Cross Section Yes/No:	Yes
Name/Location of Assembly (prime) facility:	Amkor Technology Japan – Fukuoka (DPS at Usuki)
MSL LEVEL	3
REFLOW PROFILE	260°C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	**Amkor Technology Japan – Fukuoka**

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualification of DPS Line at Usuki and assembly at Usuki site	
Marketing Part #:	S6J342AFSBEV20000
Device Description:	General purpose single-chip products
Cypress Division:	Microcontroller and Connectivity Division

PACKAGE	ASSEMBLY FACILITY SITE
100-pin LQFP	**Amkor Technology Japan – Usuki (DPS at Usuki)**

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	LQI100
Package Outline, Type, or Name:	100 – Low Profile Quad Flat Package
Mold Compound Name/Manufacturer:	EME-G660B / Sumitomo
Mold Compound Flammability Rating:	V-0
Lead Frame Material:	Copper Alloy
Lead Finish, Composition / Thickness:	Pure-Sn Plating (7 – 20um)
Die Backside Preparation Method/Metallization:	Si Back Grind
Die Separation Method:	Dicing
Die Attach Supplier:	Hitachi
Die Attach Material:	EN4600B
Wire Bond Method:	Ultrasonic & Force
Package Cross Section Yes/No:	Yes
Name/Location of Assembly (prime) facility:	Amkor Technology Japan – Usuki (DPS at Usuki)
MSL LEVEL	3
REFLOW PROFILE	260°C

ELECTRICAL TEST / FINISH DESCRIPTION	
Test Location:	**Amkor Technology Japan – Usuki**

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate	JESD22-A108, AEC Q100-008 Dynamic Operating Condition, Max. rating Voltage 125 C	P
High Temperature Operating Life Latent Failure Rate	JESD22-A108, AEC Q100-008 Dynamic Operating Condition, Max. rating Voltage, 125 C	P
High Accelerated Saturation Test (HAST)	JEDEC STD 22-A110: 130C, 85%RH, Max. rating Voltage, or 110C, 85%RH, Max. rating Voltage Precondition: JESD22 Moisture Sensitivity Level 3	P
Unbiased High Accelerated Saturation Test (UHST)	JEDEC STD 22-A110: 130C, 85%RH, Max. rating Voltage Precondition: JESD22 Moisture Sensitivity Level 3	P
Temperature Cycle	JESE22-A104 Condition C, -65C to 150C Precondition: JESD22 Moisture Sensitivity Level 3	P
High Temp Storage	JESD22-A103: 150 C, no bias	P
Acoustic Microscopy	J-STD-020 Precondition: JESD22 Moisture Sensitivity Level 3	P
Ball Shear	JESD22-B116A, Cpk : 1.67	P
Bond Pull	MIL-STD-883 – Method 2011, Cpk : 1.67	P

Reliability Test Data

QTP# 193212, 193210, 193211

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS : High Temperature Operation Life (Early failure Rate)							
S6J32GEK	4C53561	929ZZ402	Fukuoka	96	800	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	96	800	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	96	800	0	
S6J342A	S2CA1	92944015	Usuki	96	800	0	
S6J342A	S2CA1	92944021	Usuki	96	800	0	
S6J342A	S2CA1	92944022	Usuki	96	800	0	
STRESS : High Temperature Operation Life (Latent Failure Rate)							
S6J32GEK	4C53561	929ZZ402	Fukuoka	1000	77	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	1000	77	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	1000	77	0	
S6J342A	S2CA1	92944015	Usuki	1000	77	0	
S6J342A	S2CA1	92944021	Usuki	1000	77	0	
S6J342A	S2CA1	92944022	Usuki	1000	77	0	
STRESS : High Accelerated Saturation Test							
CY9BFD18	EL4558	1930837	Fukuoka	264	25	0	
CY9BFD18	EL4558	1930838	Fukuoka	264	25	0	
CY9BFD18	EL4558	1930839	Fukuoka	264	25	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	264	77	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	264	77	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	264	77	0	
S6J342A	S2CA1	92944015	Usuki	96	77	0	
S6J342A	S2CA1	92944021	Usuki	96	77	0	
S6J342A	S2CA1	92944022	Usuki	96	77	0	
STRESS : Unbiased High Accelerated Saturation Test							
CY9BFD18	EL4558	1930837	Fukuoka	96	25	0	
CY9BFD18	EL4558	1930838	Fukuoka	96	25	0	
CY9BFD18	EL4558	1930839	Fukuoka	96	25	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	96	77	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	96	77	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	96	77	0	
S6J342A	S2CA1	92944015	Usuki	96	77	0	
S6J342A	S2CA1	92944021	Usuki	96	77	0	
S6J342A	S2CA1	92944022	Usuki	96	77	0	
STRESS : Temperature Cycle							
CY9BFD18	EL4558	1930837	Fukuoka	500	25	0	
CY9BFD18	EL4558	1930838	Fukuoka	500	25	0	
CY9BFD18	EL4558	1930839	Fukuoka	500	25	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	500	77	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	500	77	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	500	77	0	
S6J342A	S2CA1	92944015	Usuki	500	77	0	
S6J342A	S2CA1	92944021	Usuki	500	77	0	
S6J342A	S2CA1	92944022	Usuki	500	77	0	

Reliability Test Data

QTP# 193212, 193210, 193211

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
STRESS : High Temperature Storage Life							
CY9BFD18	EL4558	1930837	Fukuoka	1000	25	0	
CY9BFD18	EL4558	1930838	Fukuoka	1000	25	0	
CY9BFD18	EL4558	1930839	Fukuoka	1000	25	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	1000	45	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	1000	45	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	1000	45	0	
S6J342A	S2CA1	92944015	Usuki	1000	45	0	
S6J342A	S2CA1	92944021	Usuki	1000	45	0	
S6J342A	S2CA1	92944022	Usuki	1000	45	0	
STRESS : Acoustic Microscopy							
CY9BFD18	EL4558	1930837	Fukuoka	-	22	0	
CY9BFD18	EL4558	1930838	Fukuoka	-	22	0	
CY9BFD18	EL4558	1930839	Fukuoka	-	22	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	-	22	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	-	22	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	-	22	0	
S6J342A	S2CA1	92944015	Usuki	-	22	0	
S6J342A	S2CA1	92944021	Usuki	-	22	0	
S6J342A	S2CA1	92944022	Usuki	-	22	0	
STRESS : Bong Pull post (wire number from 5 units)							
CY9BFD18	EL4558	1930837	Fukuoka	-	30	0	
CY9BFD18	EL4558	1930838	Fukuoka	-	30	0	
CY9BFD18	EL4558	1930839	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	-	30	0	
S6J342A	S2CA1	92944015	Usuki	-	30	0	
S6J342A	S2CA1	92944021	Usuki	-	30	0	
S6J342A	S2CA1	92944022	Usuki	-	30	0	
STRESS : Bong Pull (wire number from 5 units)							
CY9BFD18	EL4558	1930837	Fukuoka	-	30	0	
CY9BFD18	EL4558	1930838	Fukuoka	-	30	0	
CY9BFD18	EL4558	1930839	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ402	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ403	Fukuoka	-	30	0	
S6J32GEK	4C53561	929ZZ404	Fukuoka	-	30	0	
S6J342A	S2CA1	92944015	Usuki	-	30	0	
S6J342A	S2CA1	92944021	Usuki	-	30	0	
S6J342A	S2CA1	92944022	Usuki	-	30	0	
S6J342A	S2CA1	92944015	Usuki	-	30	0	

Document History Page

Document Title: QTP193212 DPS Line, 300mm wafer, Amkor Technology Japan Usuki Site
Document Number: 002-29439

Rev.	ECN No.	Orig. of Change	Description of Change
**	6771543	KUMI	Initial Release

Marketing Part Number	Sample Part Number	Part Number After Transfer	Samples Availability
CY9AF111KPMC-GE1	CY9AF111KPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9AF111LPMC1-G-MJE1	CY9AF111LPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF111LPMC-G-MJE1	CY9AF111LPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF111MAPMC-G-MJE1	CY9AF111MAPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF111NPMC-G-MJE1	CY9AF111NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112LPMC-G-MJE1	CY9AF112LPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112MPMC-G-MJE1	CY9AF112MPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112NPMC-G-103MJE1	CY9AF112NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112NPMC-G-104MJE1	CY9AF112NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112NPMC-G-107MJE1	CY9AF112NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF112NPMC-G-MJE1	CY9AF112NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114LAPMC1-G-MJE1	CY9AF114LAPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114LPMC1-G-MJE1	CY9AF114LPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114LPMC-G-MJ1	CY9AF114LPMC-G-MJ1KR	No Part Number Change	Subject to leadtime
CY9AF114LPMC-G-MJE1	CY9AF114LPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114MAPMC-G-MJE1	CY9AF114MAPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114NAPMC-G-F4MJE1	CY9AF114NAPMC-G-F4MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114NAPMC-G-MJE1	CY9AF114NAPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF114NPMC-G-MJE1	CY9AF114NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF116NAPMC-G-MJE1	CY9AF116NAPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF154MPMC-GE1	CY9AF154MPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9AF156NAPMC-GE1	CY9AF156NAPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9AF156NPMC-GE1	CY9AF156NPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9AF311LPMC1-G-MJE1	CY9AF311LPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF312LPMC1-G-MJE1	CY9AF312LPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF312LPMC-G-MJE1	CY9AF312LPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314LAPMC1-G-MJE1	CY9AF314LAPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314LPMC1-G-MJE1	CY9AF314LPMC1-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314LPMC-G-MJE1	CY9AF314LPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314MPMC-G-MJE1	CY9AF314MPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314NAPMC-G-MJE1	CY9AF314NAPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9AF314NPMC-G-MJE1	CY9AF314NPMC-G-MJE1KR	No Part Number Change	Subject to leadtime
CY9BF114NPMC-GE1	CY9BF114NPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF116NPMC-GE1	CY9BF116NPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF116RPMC-GE1	CY9BF116RPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF116RPMC-G-F4FKE1	CY9BF116RPMC-G-F4FKE1KR	No Part Number Change	Subject to leadtime
CY9BF116SPMC-GK7E1	CY9BF116SPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BF116TPMC-GK7FKCGE1	CY9BF116TPMC-GK7FKCGE1KR	No Part Number Change	Subject to leadtime
CY9BF128SAPMC-GK7CGE2	CY9BF128SAPMC-GK7CGE2KR	No Part Number Change	Subject to leadtime
CY9BF129SAPMC-GK7CGE2	CY9BF129SAPMC-GK7CGE2KR	No Part Number Change	Subject to leadtime
CY9BF129SPMC-GK7E1	CY9BF129SPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BF129TAPMC-GK7CGE2	CY9BF129TAPMC-GK7CGE2KR	No Part Number Change	Subject to leadtime
CY9BF218SPMC-GK7CGE1	CY9BF218SPMC-GK7CGE1KR	No Part Number Change	Subject to leadtime
CY9BF218THPMC-GK7FKCGE1	CY9BF218THPMCGK7FKCGE1KR	No Part Number Change	Subject to leadtime
CY9BF218TPMC-G-102K7E1	CY9BF218TPMC-G-102K7E1	No Part Number Change	Subject to leadtime
CY9BF218TPMC-GK7CGE1	CY9BF218TPMC-GK7CGE1KR	No Part Number Change	Subject to leadtime
CY9BF314NPMC-GE1	CY9BF314NPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF316SPMC-GK7E1	CY9BF316SPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BF318SPMC-GK7CGE1	CY9BF318SPMC-GK7CGE1KR	No Part Number Change	Subject to leadtime
CY9BF328SAPMC-GK7CGE2	CY9BF328SAPMC-GK7CGE2KR	No Part Number Change	Subject to leadtime
CY9BF414RPMC-GE1	CY9BF414RPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF416RPMC-GE1	CY9BF416RPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF429SPMC-GK7E1	CY9BF429SPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BF512NPMC-GE1	CY9BF512NPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF516RPMC-GE1	CY9BF516RPMC-GE1KR	No Part Number Change	Subject to leadtime
CY9BF518SPMC-GK7CGE1	CY9BF518SPMC-GK7CGE1KR	No Part Number Change	Subject to leadtime
CY9BF529TPMC-GK7E1	CY9BF529TPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BF618SPMC-GK7CGE1	CY9BF618SPMC-GK7CGE1KR	No Part Number Change	Subject to leadtime
CY9BF618TPMC-GK7E1	CY9BF618TPMC-GK7E1KR	No Part Number Change	Subject to leadtime
CY9BFD18SPMC-GK7FKCGE1	CY9BFD18SPMC-GK7FKCGE1KR	No Part Number Change	Subject to leadtime
CY9BFD18SPMC-GK7FKCGE1	CY9BFD18SPMC-GK7FKCGE1KR	No Part Number Change	Subject to leadtime
S6E0003H0AGV2000A	S6E0003H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C18H0AGV2000A	S6E2C18H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C1AH0AGV2000A	S6E2C1AH0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C28H0AGV2000A	S6E2C28H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C29J0AGV2000A	S6E2C29J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C2AJ0AGV2000A	S6E2C2AJ0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C38H0AGV2000A	S6E2C38H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C38J0AGV2000A	S6E2C38J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C48H0AGV2000A	S6E2C48H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C4AH0AGV2000A	S6E2C4AH0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C4AJ0AGV2000A	S6E2C4AJ0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C58H0AGV2000A	S6E2C58H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2C5AH0AGV2000A	S6E2C5AH0AGV2000Z	No Part Number Change	Subject to leadtime

S6E2C5AJ0AGV2000A	S6E2C5AJ0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2CC8H0AGV2000A	S6E2CC8H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2CC8J0AGV2000A	S6E2CC8J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2CCAL0AGL2000A	S6E2CCAL0AGL2000Z	No Part Number Change	Subject to leadtime
S6E2D35G0AGV20000	S6E2D35G0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2DH5G0AGV20000	S6E2DH5G0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2DH5J0AGV2000A	S6E2DH5J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2G26H0AGV2000A	S6E2G26H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2G26J0AGV2000A	S6E2G26J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2G26JHAGV2000A	S6E2G26JHAGV2000Z	No Part Number Change	Subject to leadtime
S6E2G28JHAGV2000A	S6E2G28JHAGV2000Z	No Part Number Change	Subject to leadtime
S6E2G36J0AGV2000A	S6E2G36J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2G38H0AGV2000A	S6E2G38H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2G38J0AGV2000A	S6E2G38J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GH6H0AGV2000A	S6E2GH6H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GH6J0AGV2000A	S6E2GH6J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GH8H0AGV2000A	S6E2GH8H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GH8J0AGV2000A	S6E2GH8J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK6H0AGV2000A	S6E2GK6H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK6HHAGV2000A	S6E2GK6HHAGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK6J0AGV2000A	S6E2GK6J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK6JHAGV2000A	S6E2GK6JHAGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK8HHAGV2000A	S6E2GK8HHAGV2000Z	No Part Number Change	Subject to leadtime
S6E2GK8J0AGV2000A	S6E2GK8J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GM6H0AGV2000A	S6E2GM6H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GM6J0AGV2000A	S6E2GM6J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GM8H0AGV2000A	S6E2GM8H0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2GM8J0AGV2000A	S6E2GM8J0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H14E0AGV2000M	S6E2H14E0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H14F0AGV2000M	S6E2H14F0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H16F0AGV2000M	S6E2H16F0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H44F0AGV2000M	S6E2H44F0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H46F0AGV2000M	S6E2H46F0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2H46G0AGV2000M	S6E2H46G0AGV2000Z	No Part Number Change	Subject to leadtime
S6E2HE6G0AGV2000M	S6E2HE6G0AGV2000Z	No Part Number Change	Subject to leadtime